

VERSION WITH MARKINGS TO SHOW CHANGES MADE

The following is a marked version of amended claims 1, 2, 3 and 6 to show changes made.

--1. (Twice Amended) A method of partially plating a substrate for electronic devices, comprising arranging [small] metal balls at selected portions of a substrate for mounting semiconductor devices thereon, and adhering or bonding the [small] metal balls thereto, and melting the [small] metal balls resulting in the metal balls being thermally diffused with the substrate, thereby selectively plating the selected portions of the substrate for electronic devices with a different metal.--

--2. (Amended) The method of partially plating a substrate for electronic devices as claimed in claim 1, wherein the method comprises provisionally arranging and holding the [small] metal balls on an arrangement base plate having through holes provided at positions corresponding to the portions to be plated of the substrate for electronic devices, transferring the arrangement base plate above the substrate for mounting electronic devices, and adhering or bonding the [small] metal balls provisionally arranged at and held by the through holes to the portions to be plated, respectively.--

--3. (Amended) The method of partially plating a substrate for electronic devices as claimed in claim 2, wherein, in the provisionally arranging and holding

procedure, excess [small] metal balls adhering to the arrangement base plate or the [small] metal balls which are provisionally held by the substrate are removed by applying vibrations to the arrangement base plate, thereby provisionally arranging and holding the [small] metal balls.--

--6. (Twice Amended) The method of partially plating a substrate for electronic devices as claimed in claim 1, wherein the [small] metal balls are selected from Au, Ag, Pd, Pt, Ni or Cr, and balls are melted by partial heating.--